

Features

- Low drain-source on-resistance: $R_{DS(ON)}=0.078\Omega(\text{typ})$
- Easy to control gate switching
- Enhancement mode: $V_{th} = 2.5 \text{ to } 4.5\text{V}$
- 100% avalanche tested
- RoHS compliant

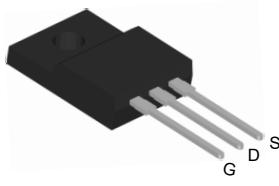
Key Performance Parameters



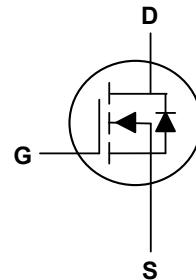
Parameter	Value	Unit
$V_{DS} @ T_{j,\max}$	650	V
$R_{DS(ON),\max}$	90	$\text{m}\Omega$
I_D	32	A
$Q_{g,\text{typ}}$	52	nC
I_{DM}	96	A

Applications

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)
- Charger, Lighting



TO-220F Top View



Absolute Maximum Ratings($T_c=25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	650	V
Gate-Source Voltage	V_{GS}	± 30	V
Continuous Drain Current ¹	I_D	32	A
Pulsed Drain Current ²	I_{DM}	96	A
Single Pulse Avalanche Energy ⁴	E_{AS}	199	mJ
Avalanche Current	I_{AS}	5.6	A
Repetitive Avalanche energy, t_{AR} limited by $T_{J,\max}$	E_{AR}	2.6	mJ
MOSFET dv/dt ruggedness, $V_{DS} = 0 \dots 400\text{V}$	dv/dt	50	V/ns
Reverse diode dv/dt ³ $V_{DS}=0 \dots 400\text{V}$, $I_{SD} \leq I_D$		50	
Total Power Dissipation ($T_c=25^\circ\text{C}$)	P_D	43	W
Storage Temperature Range	T_{STG}	-55 to 150	°C
Operating Junction Temperature Range	T_J	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance Junction-Ambient	$R_{\theta JA}$	62.5	°C/W
Thermal Resistance Junction-Case	$R_{\theta JC}$	2.9	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	650	---	---	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}$, $I_D=15.3\text{A}$	---	78	90	$\text{m}\Omega$
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}$, $I_D = 1.7\text{mA}$	2.5	---	4.5	V
Drain-Source Leakage Current	I_{DSS}	$V_{\text{DS}}=650\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	μA
Gate-Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 30\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
Gate Resistance	R_G	$f = 1.0\text{MHz}$, open drain	---	1.2	---	Ω
Total Gate Charge	Q_g	$V_{\text{DD}}=400\text{V}$, $V_{\text{GS}}=10\text{V}$, $I_D=10\text{A}$	---	52	---	nC
Gate-Source Charge	Q_{gs}		---	12.7	---	
Gate-Drain Charge	Q_{gd}		---	22.4	---	
Turn-On Delay Time	$T_{d(\text{on})}$	$V_{\text{DD}}=400\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_G=10\Omega$, $I_D=15.3\text{A}$	---	17	---	ns
Rise Time	T_r		---	10	---	
Turn-Off Delay Time	$T_{d(\text{off})}$		---	86	---	
Fall Time	T_f		---	11	---	
Input Capacitance	C_{iss}	$V_{\text{DS}}=400\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	2270	---	pF
Output Capacitance	C_{oss}		---	58	---	
Reverse Transfer Capacitance	C_{rss}		---	9	---	

Drain-Source Diode Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Continuous Source Current	I_S	$T_C=25^\circ\text{C}$	---	---	32	A
Pulsed Source Current	I_{SM}		---	---	96	A
Diode Forward Voltage	V_{SD}	$V_G=0\text{V}$, $I_S=15.3\text{A}$, $T_J=25^\circ\text{C}$	---	---	1.2	V
Reverse Recovery Time	t_{rr}	$V_R=400\text{V}$, $I_F=15.3\text{A}$, $dI_F/dt=100\text{A}/\mu\text{s}$	---	346	---	ns
Reverse Recovery Charge	Q_{rr}		---	5.1	---	μC
Peak Reverse Recovery Current	I_{rrm}		---	20	---	A

Note:

1. Limited by $T_{j,\text{max}}$. Maximum Duty Cycle D = 0.50
2. Pulse width t_p limited by $T_{j,\text{max}}$
3. Identical low side and high side switch with identical R_G
4. $V_{\text{DD}}=50\text{V}$, $R_G=25\Omega$, $I_{AS}=5.6\text{A}$

Typical Characteristics

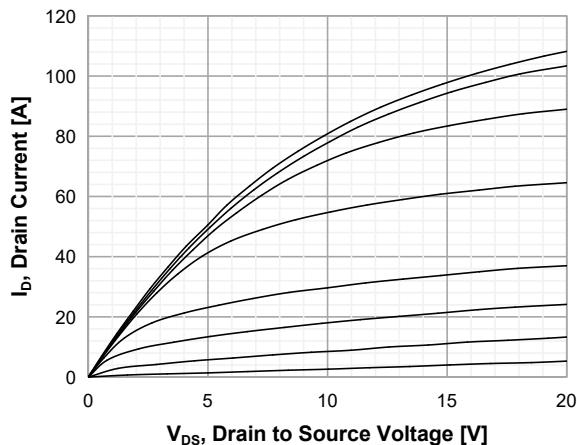


Figure 1. On-Region Characteristics

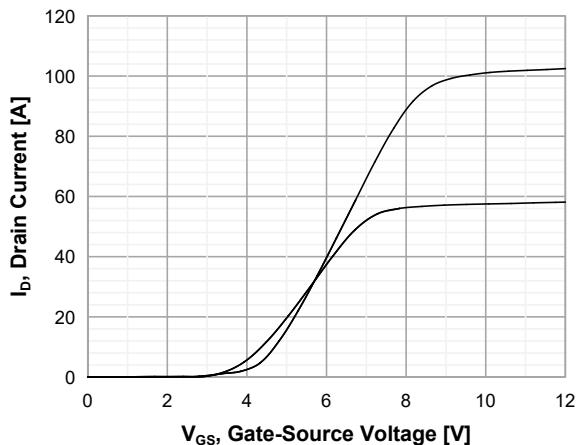


Figure 2. Transfer Characteristics

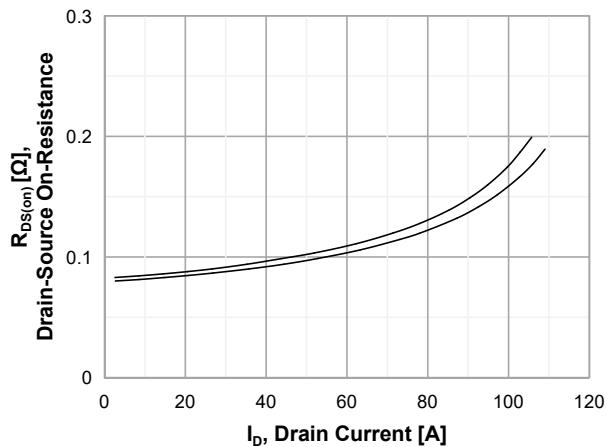


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

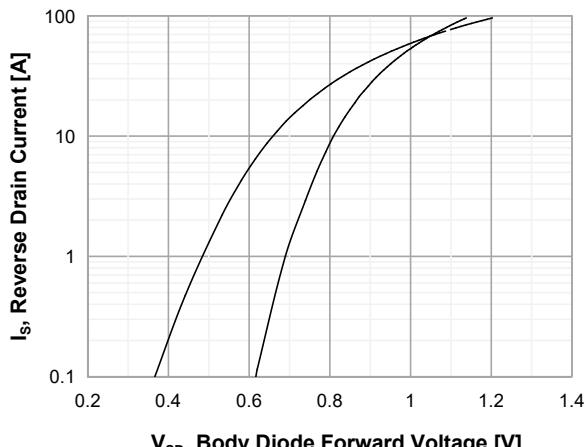


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

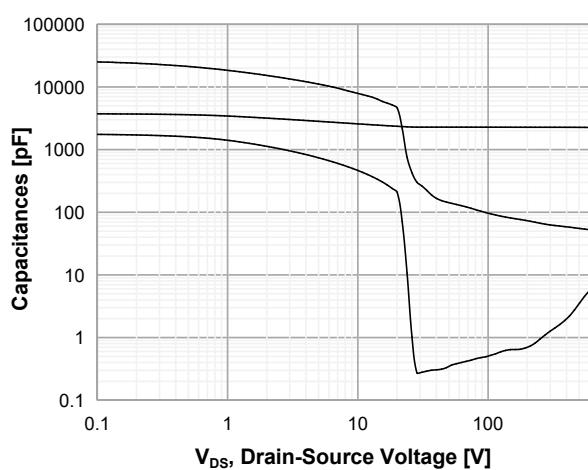


Figure 5. Capacitance Characteristics

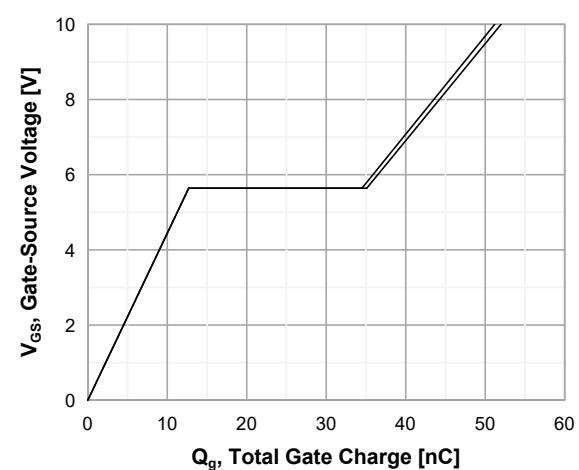
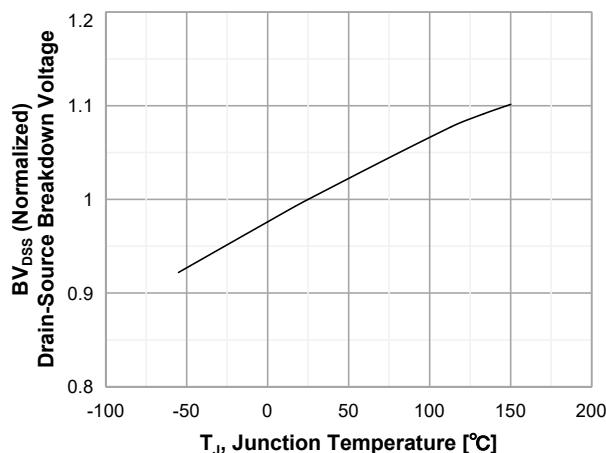
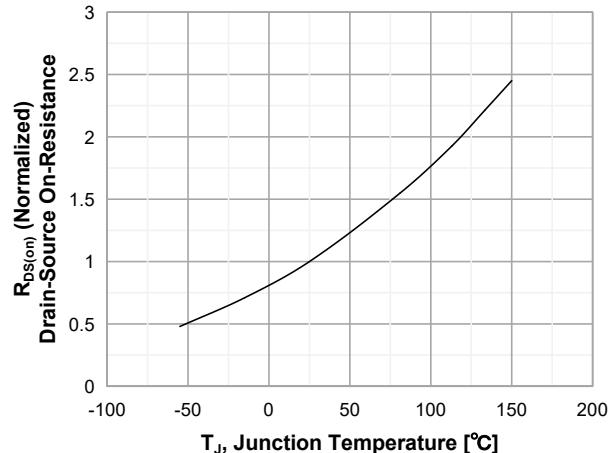


Figure 6. Gate Charge Characteristics



**Figure 7. Breakdown Voltage Variation
vs Temperature**



**Figure 8. On-Resistance Variation
vs Temperature**

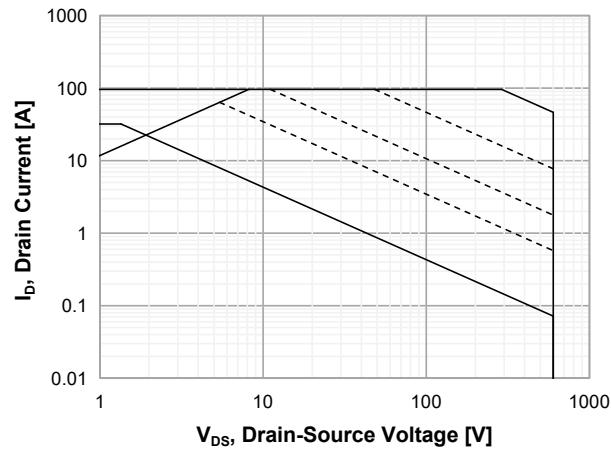
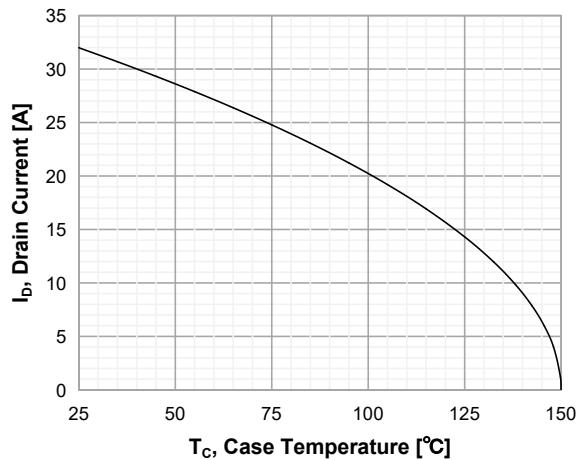


Figure 9. Maximum Safe Operating Area



**Figure 10. Maximum Drain Current vs.
Case Temperature**

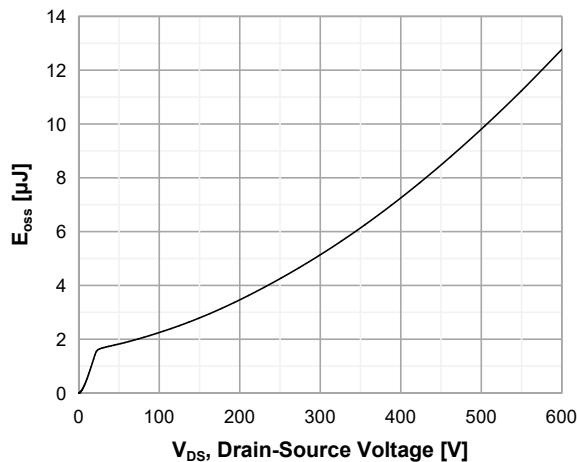


Figure 11. E_{oss} vs. Drain to Source Voltage

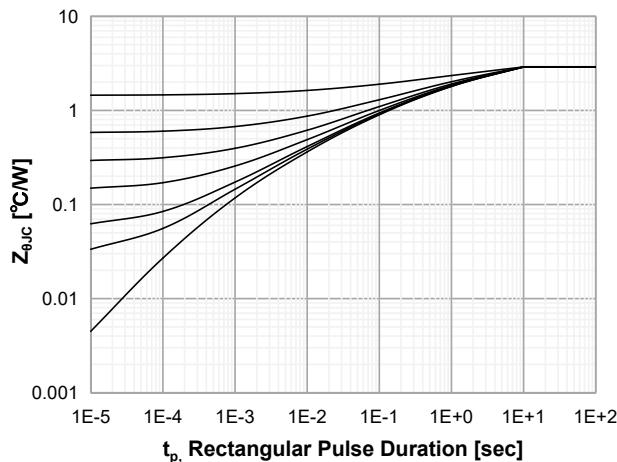
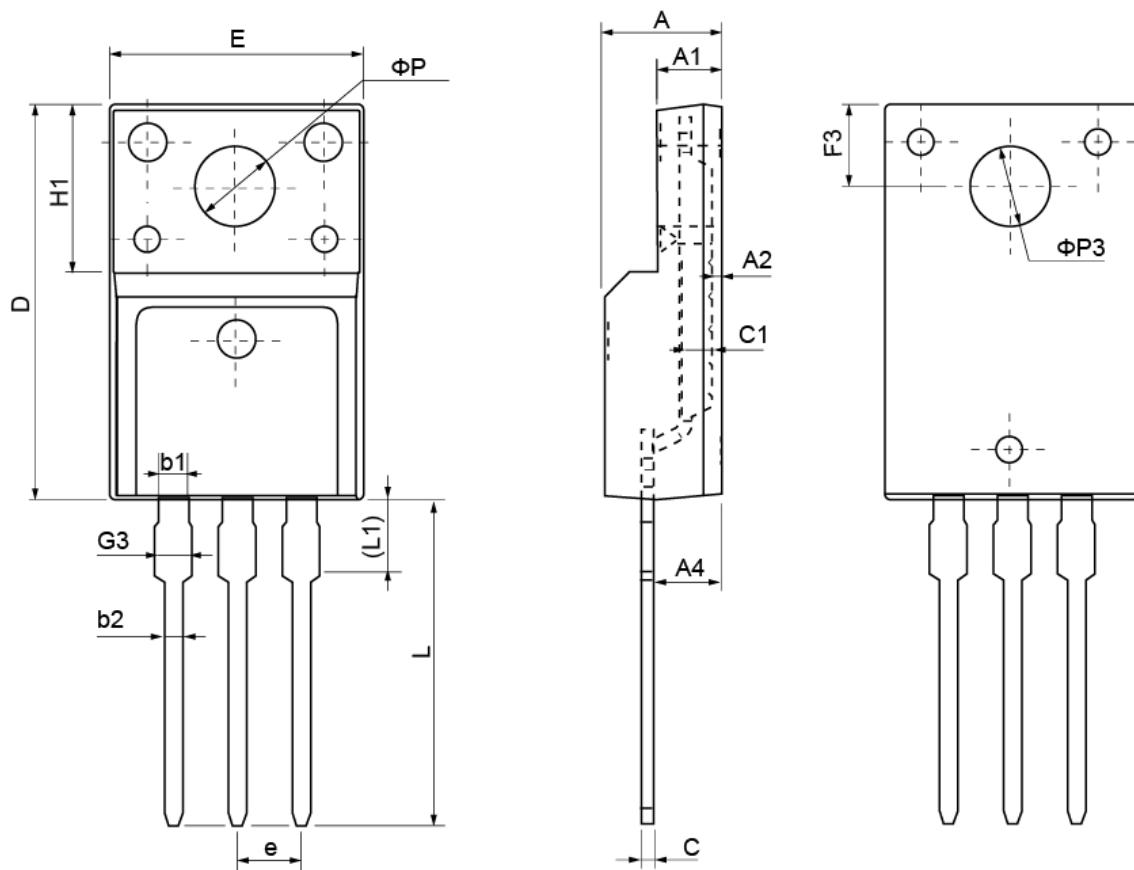


Figure 12. Transient Thermal Response Curve

TO-220F Package Outline Dimensions



Symbol	Dimensions (unit:mm)			Symbol	Dimensions (unit:mm)		
	Min	Typ	Max		Min	Typ	Max
A	4.40	4.70	5.00	H1	6.70 REF		
A1	2.30	2.55	2.80	L	12.30	12.98	13.30
A2	0.30	0.50	0.70	L1	2.95	3.10	3.50
A4	2.45	2.80	3.05	φ P	3.03	3.20	3.50
c	0.30	0.50	0.70	φ P3	3.15	3.45	3.65
c1	1.20	1.30	1.40	b1	1.10	1.30	1.45
D	15.40	15.90	16.40	b2	0.60	0.80	1.00
E	9.86	10.16	10.46	F3	3.05	3.30	3.55
e	2.54 BSC			G3	1.15	1.35	1.55



Printing Information

ATC =====Brand

XXXXXXX =====Material Code

XXYY =====XX Representative Year
YY Representative Weeks